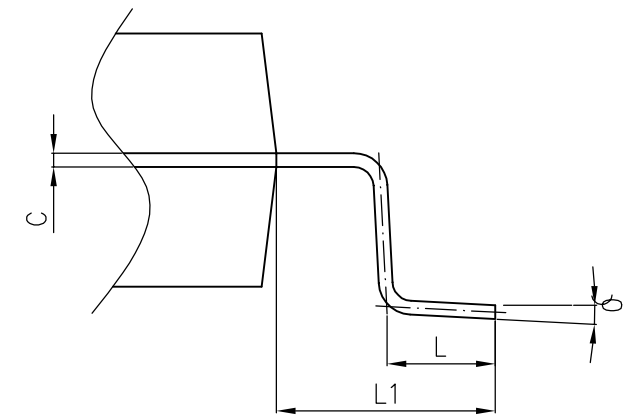
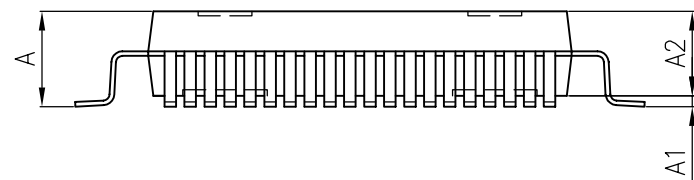


BOTTOM E-PIN INDENT #2 ϕ 0.110
NOTE 6



NOTE :

1. CONTROLLING DIMENSION : INCH
2. LEAD FRAME MATERIAL : C7025
3. AFTER SOLDER PLATING LEAD THICKNESS WILL BE 0.008" MAX.
4. PACKAGE DIMENSION EXCLUSIVE MOLDING FLASH.
5. RESIN PROTRUSION BETWEEN LEAD TO LEAD SHALL NOT EXCEED 0.006" PER SIDE.
6. BOTTOM E-PIN INDENTS ARE MARKED AS BELOW:

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	—	—	3.40	—	—	0.134
A1	0.25	—	—	0.010	—	—
A2	2.54	2.79	3.05	0.100	0.110	0.120
b	0.23	—	0.38	0.009	—	0.015
C	0.13	0.15	0.20	0.005	0.006	0.008
E	18.57	18.82	19.08	0.731	0.741	0.751
E1	13.89	13.99	14.10	0.547	0.551	0.555
D	24.56	24.82	25.07	0.967	0.977	0.987
D1	19.89	19.99	20.09	0.783	0.787	0.791
e	—	0.65	—	—	0.0256	—
L	1.07	1.19	1.35	0.042	0.047	0.053
L1	2.34	2.41	2.49	0.092	0.095	0.098
θ	0°	—	7°	0°	—	7°
y	0.00	—	0.076	0.000	—	0.003

TAIWAN NO
#1

XY
#2

X : A ~ M
Y : 1 ~ 6
NO : DENOTE MOLD SET NUMBER

CUSTOMER :

LINGSEN 5-1 NAN 2ND ROAD T.E.P.Z
PRECISION IND, LTD TAICHUNG, TAIWAN. R. O. C

APPROVED BY

DATE

TITLE :
100L QFP PACKAGE OUTLINE
DRAWING(14x20 mm)
FOOTPRINT:4.8 mm

DRAW BY:

Vicky Chen

01/04/'99

CHECK BY:

Thomas Kao

01/05/'99

APPROVAL:

Paul Liu

01/06/'99

APPROVAL:

Barry Chen

01/06/'99

DWG. NO. PO-QFP-003

REV. 0

UNIT : INCH

SCALE : 4/1

SHEET 1 OF 1